

## **IN THE CLAIMS**

CLAIMS 1 – 6 (Canceled)

CLAIM 7 (Allowed) A method according to claim 49 wherein said sheet is spaced apart from said surface by a flexible support.

CLAIMS 8 – 9 (Canceled)

CLAIM 10 (Allowed) A method according to claim 7 wherein said sheet and said flexible support forms a space containing said plurality of elongated electrical conductors.

CLAIMS 11 – 40 (Canceled)

CLAIM 41 (Allowed) A method comprising:

providing a substrate having a surface;

forming a plurality of elongated electrical conductors extending away from said surface; each of said elongated electrical conductors having a first end affixed to said surface and a second end projecting away from said surface;

there being a plurality of said second ends;

providing a means for maintaining said plurality of said second ends in substantially fixed positions with respect to each other.

CLAIM 42 (Allowed) A method according to claim 41 wherein said means for maintaining is a sheet formed from a material selected from the group consisting of Invar, Cu/Invar/Cu, molybdenum and polyimides.

CLAIM 43 (Allowed) A method according to claim 41 wherein said means for maintaining is a sheet formed from a material selected from the group consisting of a metal, a polymer, a semiconductor and dielectric.

CLAIMS 44 – 48 (Canceled)

CLAIM 49 (Allowed) A method according to claim 41 wherein said means for maintaining comprises a sheet of material comprising openings comprising a large region and a small region.

CLAIM 50 (Canceled)

CLAIM 51 (Allowed) A method according to claim 41 wherein said means for maintaining comprises openings comprising a large region and a small region, said compliant elongated electrical conductors are first inserted through said large region and then moved to said small region.

CLAIMS 52 – 57 (Canceled)

CLAIM 58 (Allowed) A method according to claim 41 wherein said means for maintaining is a sheet of material comprising a plurality of openings through which said second ends project.

CLAIM 59 (Allowed) A method according to claim 41 wherein said means for maintaining comprises at least one sheet of material comprising a plurality of openings through which said second ends project.

CLAIM 60 (Allowed) A structure according to claim 59 wherein of said at least one sheet is a sheet of electrically conductive material which has a top surface and a bottom surface and said openings have a sidewall, a dielectric material coats said top surface and said bottom surface and said sidewall.

CLAIM 61 – 63 (Canceled)

CLAIM 64 (Allowed) The structure according to claim 51 wherein each of said elongated electrical conductors projects through one of said openings in said sheet of material.

CLAIM 65 (Allowed) The structure according to claim 58 wherein each of said elongated electrical conductors projects through one of said plurality of openings in said sheet of material.

CLAIM 66 (Allowed) The structure according to claim 59 wherein each of said elongated electrical conductors projects through one of said plurality of openings in said sheet of material.

CLAIM 67 (Allowed) The structure according to claim 41 wherein said means for maintaining comprises openings which are larger in size than said elongated electrical conductor and wherein each of said elongated electrical conductors projects through one of said openings in said sheet of material.

CLAIM 68 (Allowed) The structure according to claim 58 wherein each of said plurality of openings is larger in size than said elongated electrical conductor.

Claim 69 (New) A method of effecting temporary connections to free ends of at least a portion of a plurality of elongate spring contact elements mounted to and extending from an electronic component such as a semiconductor device, the method comprising:

urging the electronic component against an interconnection substrate so that the free ends of at least a portion of the spring contact elements vertically contact selected ones of a corresponding plurality of terminals on the interconnection substrate;

providing a rigid planar member between the electronic component and the interconnection substrate;

providing a plurality of guide holes in the rigid planar member; and

inserting the free ends of at least a portion of the spring contact elements extending through selected ones of the guide holes.